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ABSTRACT OF THE DISCLOSURE

CURING ACCELERATOR, EPOXY RESIN COMPOSITION, AND SEMICONDUCTOR DEVICE

A curing accelerator which is suitable for various curable resin compositions, an epoxy resin composition having excellent curability, storage stability and fluidity, and a semiconductor device having excellent solder cracking resistance and moisture resistance reliability are provided. The epoxy resin composition includes a compound (A) having two or more epoxy groups in one molecule, a compound (B) having two or more phenolic hydroxyl groups in one molecule, trisubstituted phosphoniophenolate or a salt thereof as a curing accelerator (C), and an inorganic filler (D).

No Figure



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